

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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RF Power MOSFET Transistor 150 W, 100 - 500 MHz, 28 V

Rev. V1

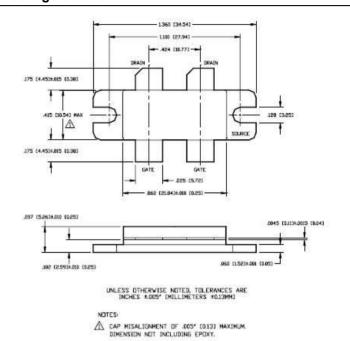
Features

- DMOS structure
- Lower capacitance for broadband operation
- Common source configuration

ABSOLUTE MAXIMUM RATINGS^{1, 2, 3}

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	65	V
Gate-Source Voltage	V _{GS}	20	V
Drain-Source Current	I _{DS}	16*	Α
Power Dissipation	P _D	389	W
Junction Temperature	TJ	200	°C
Storage Temperature	T _{STG}	-65 to +150	°C
Thermal Resistance	Θ _{JC}	0.45	°C/W

Package Outline



- 1. Exceeding any one or combination of these limits may cause permanent damage to this device.
- 2. M/A-COM does not recommend sustained operation near these maximum limits.
- 3. At 25°C Tcase, unless noted.

ELECTRICAL SPECIFICATIONS: 25°C

Parameter	Test Conditions	Units	Min.	Max.
Drain-Source Breakdown Voltage	V _{GS} = 0.0 V, I _{DS} = 20.0 mA*	BV _{DSS}	65	_
Drain-Source Leakage Current	V _{DS} = 28.0 V, V _{GS} = 0.0V*	I _{DSS}	_	4.0
Gate-Source Leakage Current	V _{GS} = 20 V, V _{DS} = 0.0 V*	I _{GSS}	_	4.0
Gate Threshold Voltage	V _{DS} = 10.0 V, I _{DS} = 400.0 mA*	$V_{GS(TH)}$	2.0	6.0
Forward Transconductance	V_{DS} = 10.0 V, I_{DS} = 4000.0 mA, ΔV_{GS} = 1.0 V, 80 μ s pulse*	G _M	2.0	_
Input Capacitance	V _{DS} = 28.0V, F = 1.0 MHz*	C _{ISS}	_	180
Output Capacitance	V _{DS} = 28.0V, F = 1.0 MHz*	Coss	_	120
Reverse Capacitance	V _{DS} = 28.0V, F = 1.0 MHz*	C _{RSS}	_	32
Power Gain	V _{DD} = 28.0 V, I _{DQ} = 400.0 mA, P _{OUT} = 150.0 W, F = 500 MHz	G _P	8	_
Drain Efficiency	V _{DD} = 28.0 V, I _{DQ} = 400.0 mA, P _{OUT} = 150.0 W, F = 500 MHz	η _D	55	_
Load Mismatch Tolerance	V _{DD} = 28.0 V, I _{DQ} = 400.0 mA, P _{OUT} = 150.0 W, F = 500 MHz	VSWR-T	_	10:1**

Notes:

1

^{*} Per side

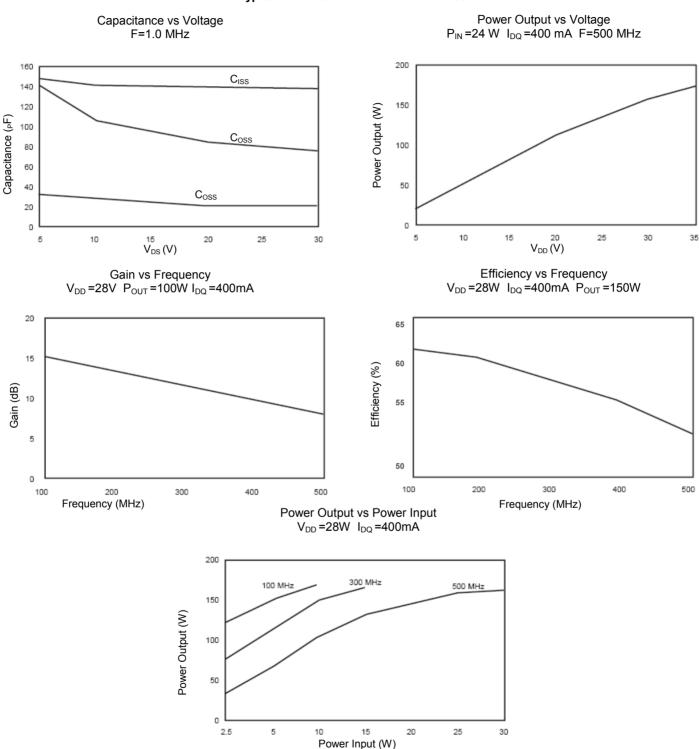
^{**} At all phase angles



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Typical Broadband Performance Curves



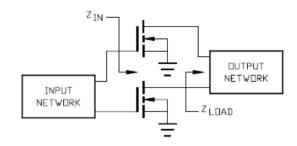


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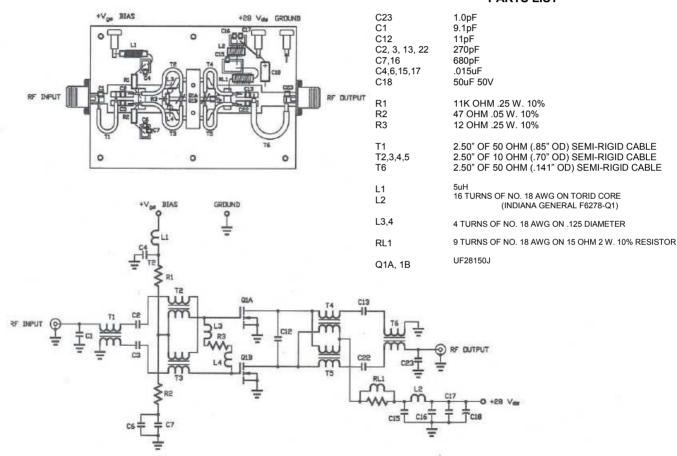
Rev. V1

TYPICAL OPTIMUM DEVICE IMPEDANCES

F (MHz)	Z _{IN} (Ω)	Z _{LOAD} (Ω)		
100	3.7 - j5.9	3.0 - j0.7		
300	2.7 - j5.9	2.6 - j0.55		
500	2.5 - j2.9	2.5 - j0.5		
V _{DD} = 28V, I _{DQ} = 400mA, P _{OUT} = 150W				



PARTS LIST



HANDLING PROCEDURES: STATIC SENSITIVITY

Please observe the following precautions to avoid damage:

DMOS devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.

UF28150J



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